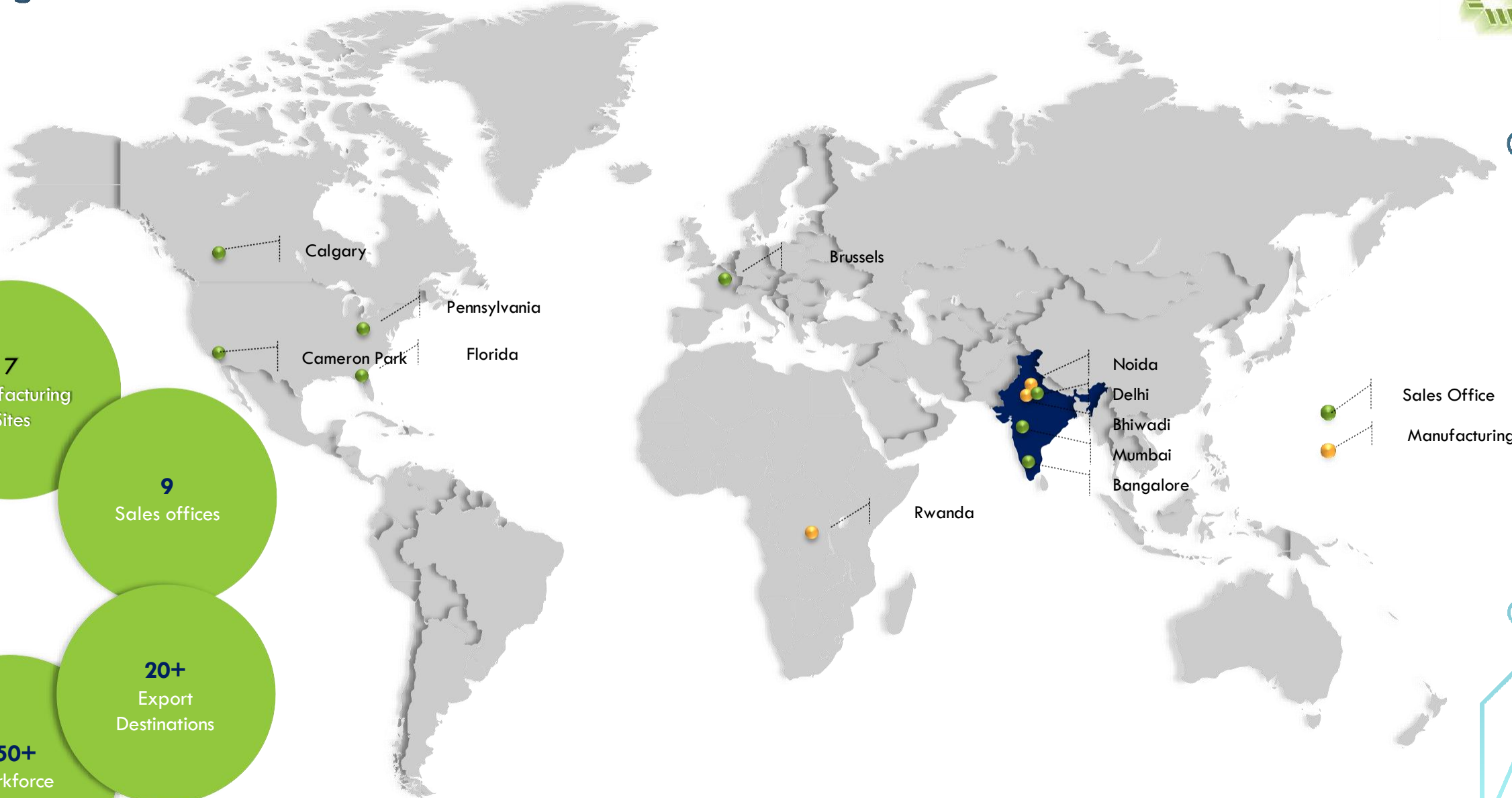
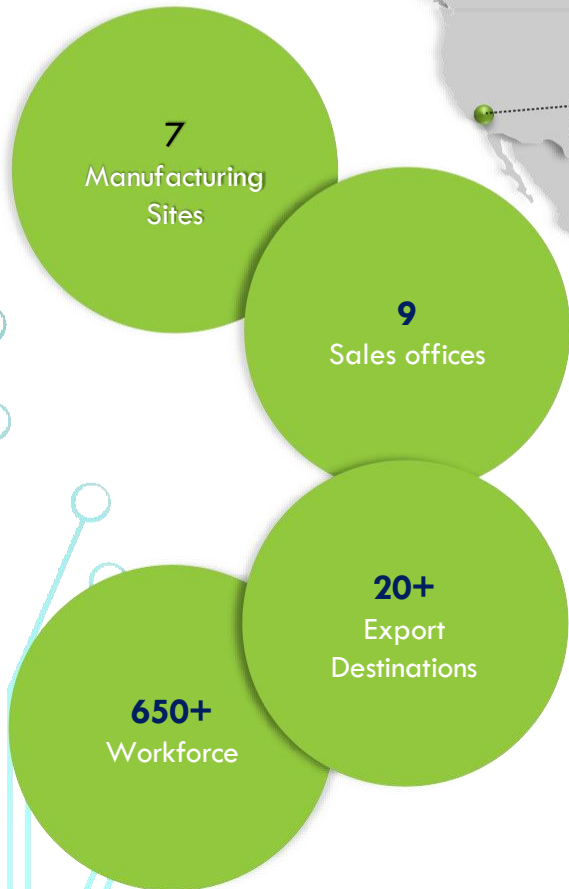
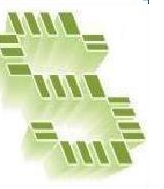


SAHASRA ELECTRONICS

“We Assemble Relationships” ➤

The background of the slide is a solid green color. In the lower right quadrant, there is a cluster of overlapping circles in various shades of green, ranging from light to dark. These circles vary in size and are arranged in a way that creates a sense of depth and movement, resembling a bubble or particle effect.

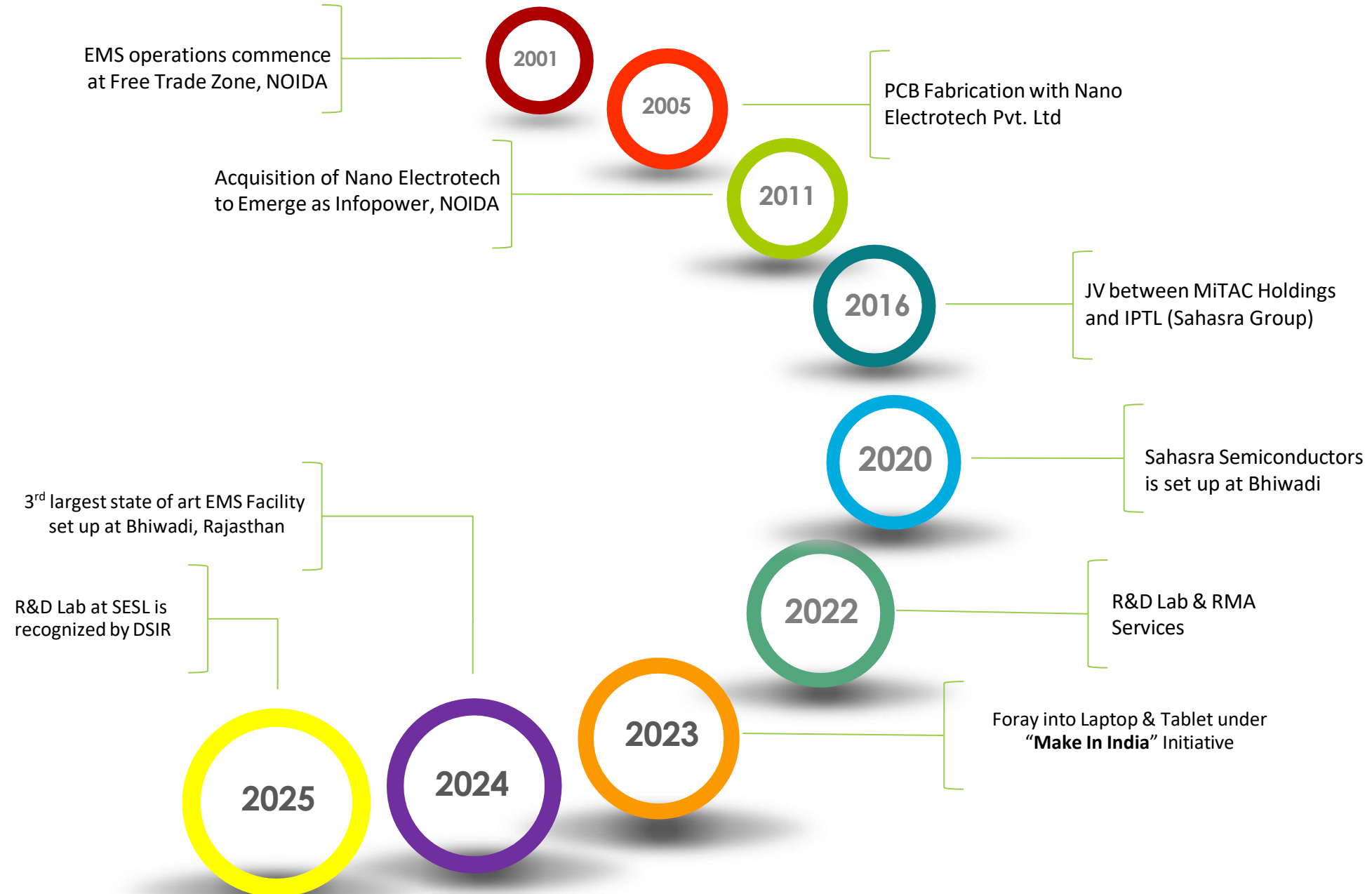
COMPANY OVERVIEW



Sales Office

Manufacturing Sites

KEY MILESTONES





QUALITY MANAGEMENT - CERTIFICATIONS

ANSI ESD S20.20

Gained ESD certification in 2015.
Certified by UL/DQS

ISO9001

ISO9001 certified in 2004. Certified by TUV

ISO/TS16949_Automotive

Automotive quality management system certified in 2015. Certified by TUV

ISO/TS 22163_IRIS Railways

Railway quality management system certified in 2017. Certified by TUV

AS9100D_Aerospace

Aerospace quality management system certified in 2023. Certified by TUV

2001-2005

2011-2015

2016-2018

2019-2021

2022-2026

ISO14001/ OHSAS18001

Environmental & OHSAS certified in 2014. Certified by TUV

Sony Green Partner

Certification

Green Partner Environmental Quality in 2017. Certified by SONY

IATF16949_Automotive

Upgraded to IATF16949 in Dec. 2018.
Certified by TUV

ISO 13485_Medical

Medical quality management system certified in 2021. Certified by BSi

ISO45001 (OH&S)

Upgraded the certificate in Jan. 2021.
Certified by TUV

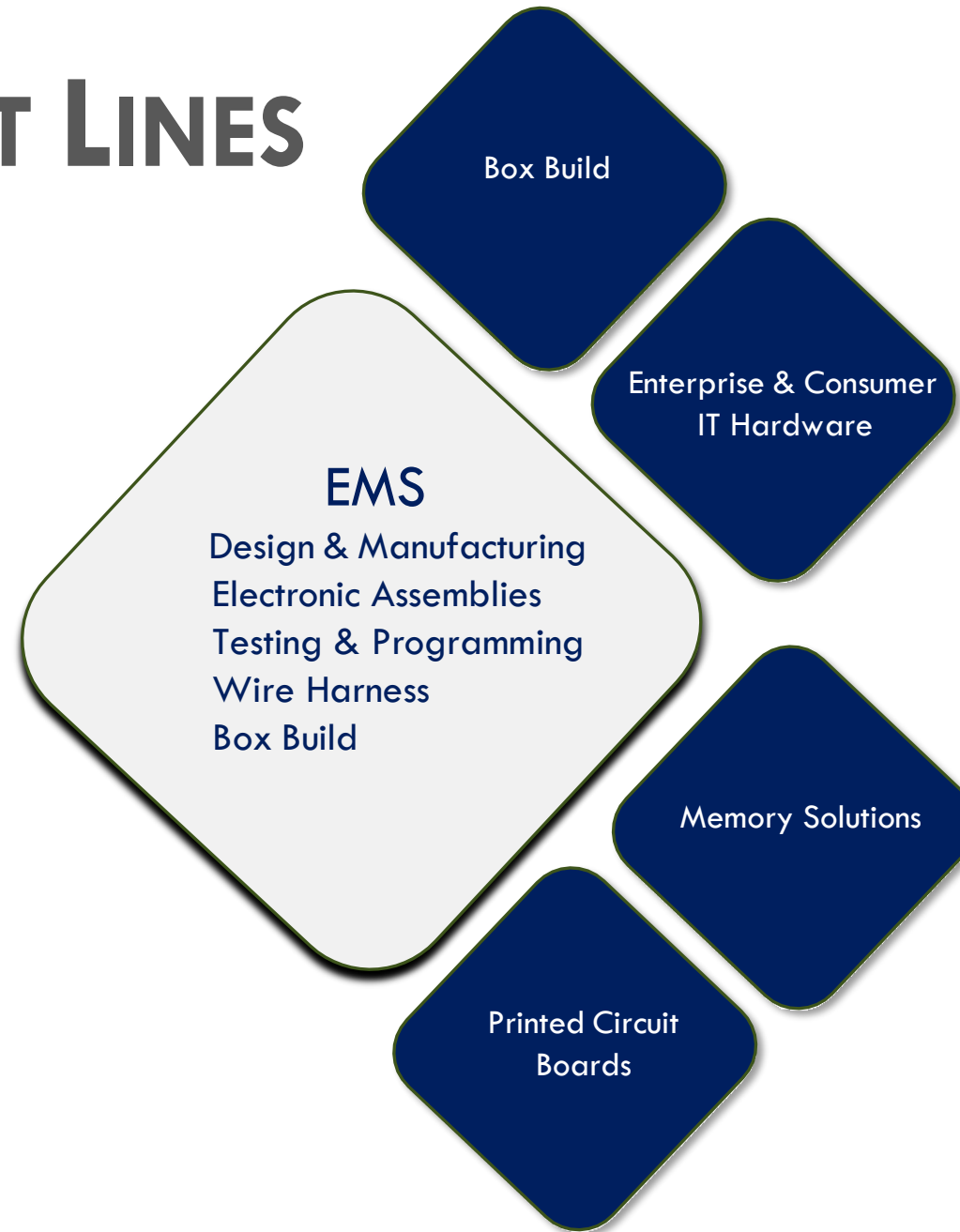
ISO 27001:2022_ISMS

Certified by DQS

IATF 16949:2016_Automotive

Certified by DQS

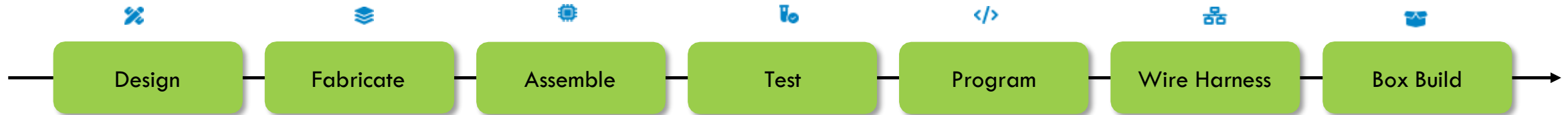
PRODUCT LINES





ELECTRONIC MANUFACTURING SERVICES

PRODUCT INTEGRATION LIFECYCLE



MANUFACTURING ENGINEERING

DESIGN FOR MANUFACTURING (DFM / DFA)

Manufacturing Friendly Design

Reduced Cycle Time

Lower Cost

Higher Quality & Reliability

✓ Right Design. Right Process. Right Quality.

SIMULATION & DIGITAL TWIN

3D PCBA Virtualization

Virtual Prototype & Validation

Design Issue Detection

Thermal & Stress Analysis

Process Simulation & Optimization

Faster Time to Market

✓ Simulate Today. Perfect Tomorrow.

Faster | Cheaper | Better

MANUFACTURING INFRASTRUCTURE



(4+8) Fully Automated High-Speed Fuji SMT Lines

PRODUCT PORTFOLIOS | CAPABILITIES



WIRE HARNESS, INJECTION MOLDING & SHEET METAL

END-TO-END MANUFACTURING SOLUTIONS



WIRE HARNESS



INJECTION MOLDING



SHEET METAL



HIGH QUALITY



PRECISION
MANUFACTURING



EXPERIENCED
TEAM



ON-TIME
DELIVERY



COST
EFFECTIVE



RELIABLE
SOLUTIONS

MATERIALS & COMPONENTS

Box Build Material

- Plastic Parts & Custom Molded Enclosures
- Metal Parts & Precision Sheet Metal Assemblies
- Rubber Parts, Gaskets & Protective Seals
- Silicon Keypads & User-Interface Panels



TECHNICAL SPECIFICATIONS

Wire Harness Capabilities

- Single Wire Size: 32 – 16 AWG (0.03 – 1.30 mm²)
- Multicore / Cable OD: 32 – 16 AWG gauge range
- Multicore / Cable OD: 32 – 16 AWG
- Stripping Length: 0 – 9,999 mm



- Cutting Length: 30 – 9,999 mm



- Stripping Length: 0 – 300 mm



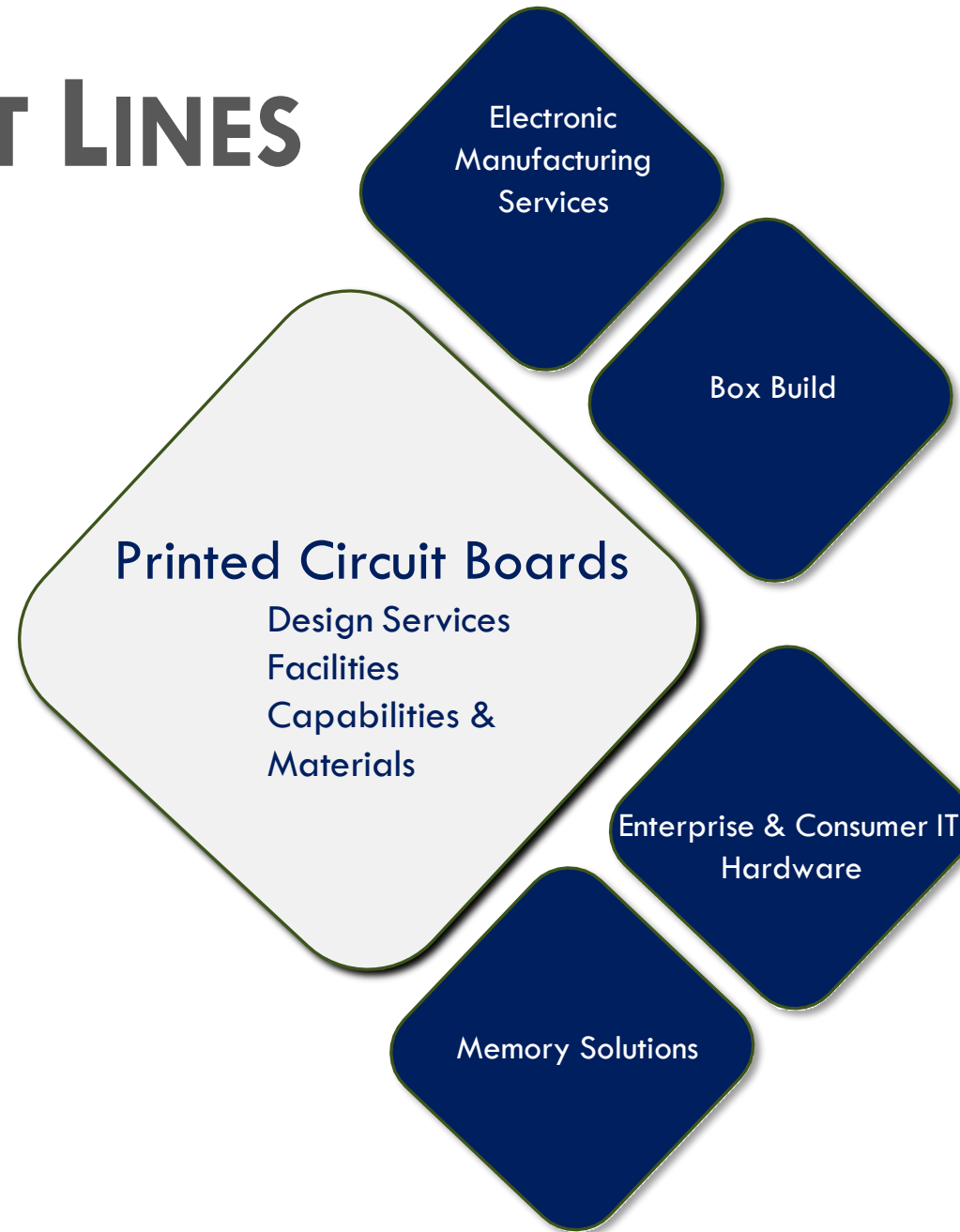
- Crimping Force: Up to 2 tons force capability



- Parallel Crimping: Up to 20 wires processed simultaneously

PRECISION MANUFACTURING SOLUTIONS

PRODUCT LINES



PCB DESIGN SERVICES

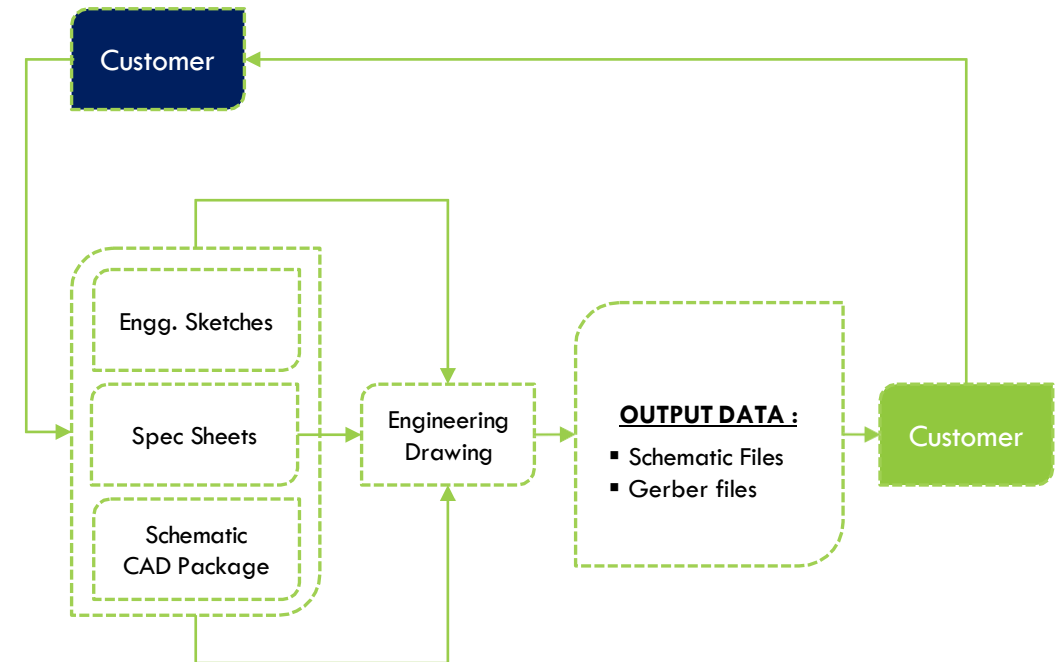


CAPABILITIES & TOOLSTACK

Design Capabilities & Standards

- **Engineering Team:** Well-qualified and highly experienced PCB design engineers.
- **Industry Standards:** 100% IPC-2220 compliance for rigid PCB design and performance.
- **EDA Software:** Altium Designer, Cadence Allegro for high-speed & complex layout.
- **CAM Software:** EzCAM, CAM350, GCCAM for comprehensive tooling & DFM validation.
- **Design Scope:** Single Sided (S/S), Double Sided (D/S), Multi-Layer (M/L), and SMT technologies.

DESIGN PROCESS & DELIVERABLES



FABRICATION CAPABILITIES & MATERIALS



SUBSTRATES & SUPPLIERS

Materials

- **Substrates:** FR-4, FR-4 High TG, Al Substrate, CEM-1 / CEM-3, KB
- **Laminates & Resin:** Isola, Nanya, C-Sem
- **Consumables:** Hitachi Dry Film, Taiyo Solder Mask Ink
- **Tooling & Chemistry:** Kemmer Drill Bits, Atotech Chemicals

PRECISION & DIMENSIONS

Process Capability

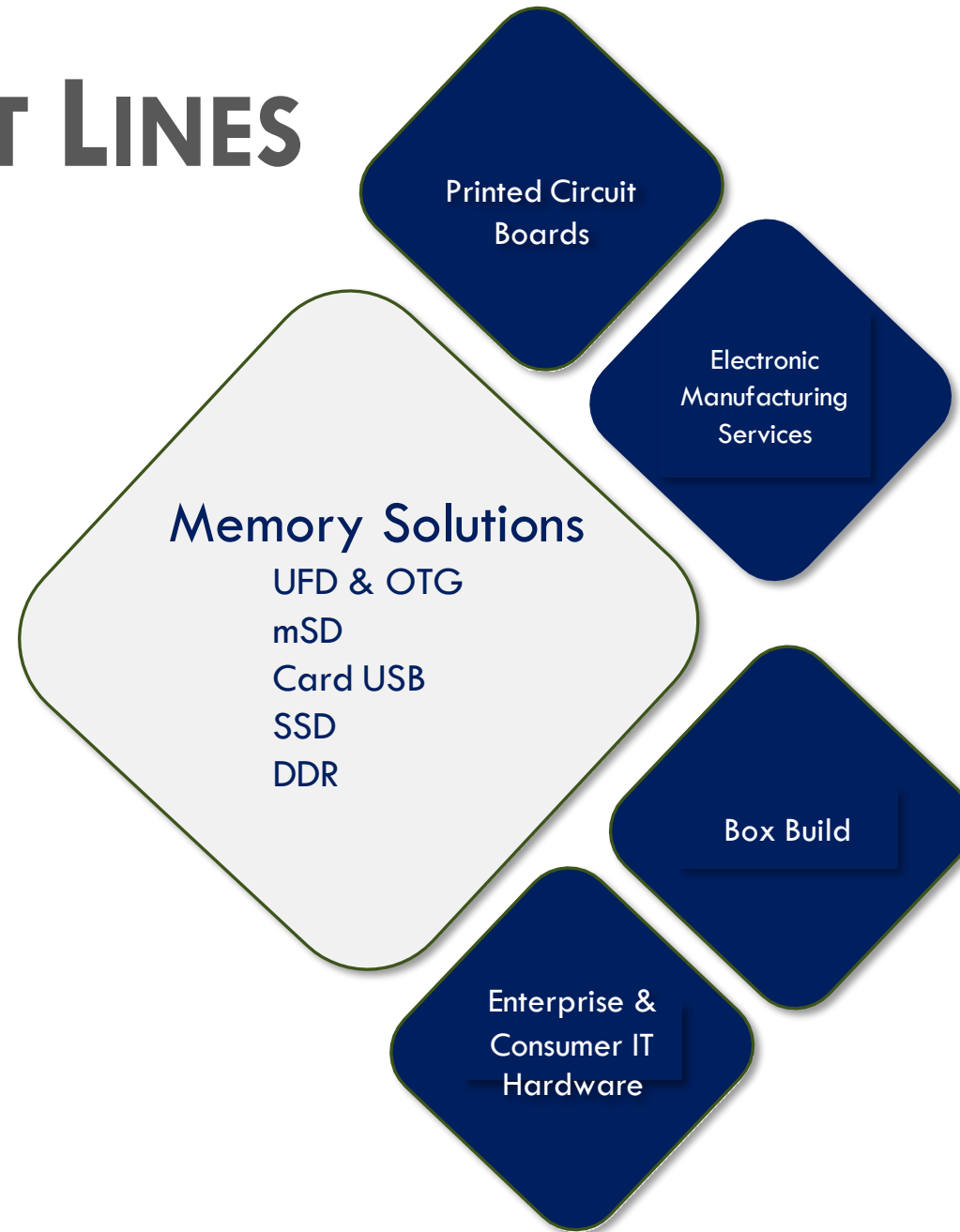
- **Board Thickness:** 0.2mm – 3.2mm
- **Panel Sizes:** 1220x406mm (SS), 610x354mm (DS), 610x305mm (ML)
- **Copper Weight:** 0.75 to 4 Oz
- **Line / Space:** 4/4 mil line width and spacing
- **Hole & Pitch:** 0.15mm PTH hole size | SMT pitch 20 mil
- **Advanced Features:** Blind & Buried Vias, Controlled Impedance

PCB TYPES & FINISHES

PCB Type & Finish

- **Board Structures:** Single Side, Double Side, Multi Layer (10 Layers), Aluminum Metal Core
- **Solder Mask Options:** Black, Blue, Green, White, Red Solder Mask
- **Surface Finishes:** LF-HAL, Immersion Gold, OSP and HAL finish
- **Silkscreen Colors:** Orange, Grey, Black, White, Yellow Silkscreen
- **Specialized Coatings:** Peelable Mask

PRODUCT LINES



OVERVIEW

KEY OEM CUSTOMERS & RETAILERS

Sony

HP

SILICON POWER

CENTON

DELKIN

AMAZON



SSD (Solid State Drive)

CONSUMER GRADE

- 2.5" SATA III SSD Internal
- M.2 NVMe 2280 SSD Internal
- USB 3.1 Gen 1 Portable
- Capacity: 128GB to 4TB

ENTERPRISE GRADE

- 2.5 Inch SATA III Internal



USB Flash Drive

- USB 2.0 Flash Drive
- USB 3.1 Flash Drive
- USB OTG Flash Drive
- Capacity: 8GB to 512GB



Micro SD Card

- Class 4 Series
- Class 6 Series
- Class 10 Series
- Extreme Series
- Capacity: 2GB to 512GB
- Class 10 to UHS Speed Class 3 (U3) suitable for 4K Video recording

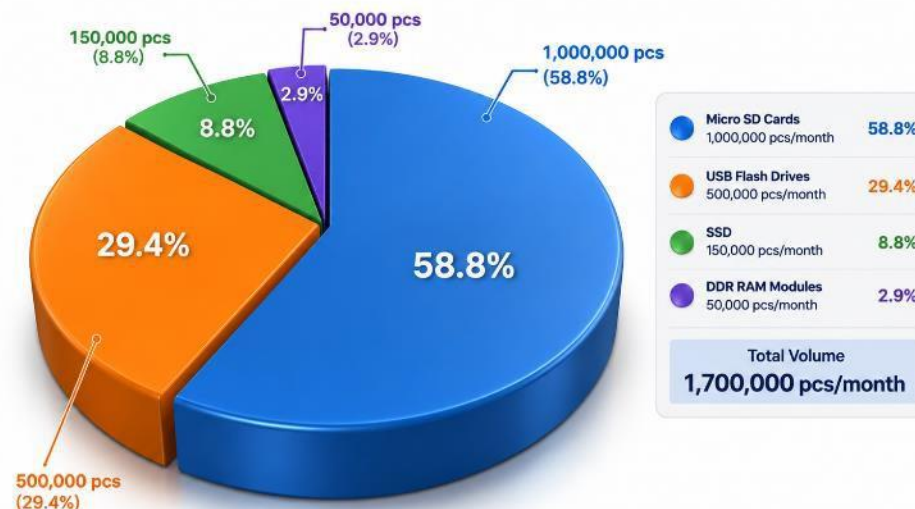


DDR RAM

- DDR3 1600
- DDR4 2666 / 3200
- DDR5 4800 / 5200 / 5600
- SO-DIMM / U-DIMM
- Capacity ranging between 4GB to 32GB

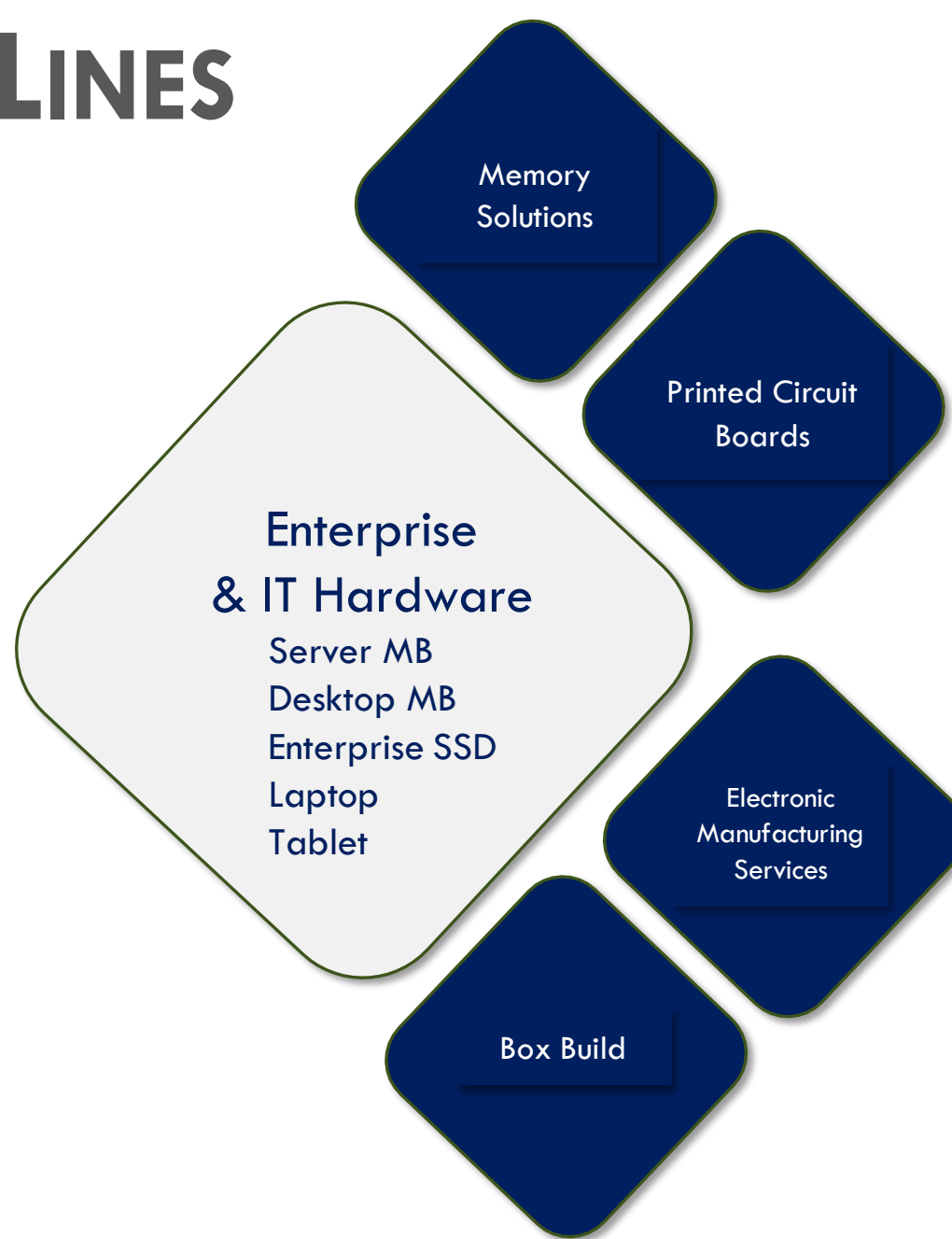
Monthly Product Mix – Storage & Memory Products

Total Volume: 1,700,000 pcs/month



SMALL PRODUCTS. BIG POSSIBILITIES.

PRODUCT LINES



ENTERPRISE & INDUSTRIAL IT HARDWARE



Product & Hardware Offerings

Enterprise & Industrial Motherboards

High-reliability Motherboards engineered specifically for servers, edge computing, and industrial applications.



Enterprise Grade Servers & SSDs

Robust server systems and enterprise SSD storage solutions tailored for data centers and mission-critical tasks.



Industrial & Consumer Grade Tablets

Versatile tablet solutions designed for rugged field applications as well as consumer operations.



Embedded Boards, Box PCs & Panel PCs

Industrial and enterprise grade embedded platforms, compact Box PCs, and integrated touch Panel PCs.



Key Milestones & Capabilities

- **Pioneer in Server MBs**

India's first company to manufacture Server Grade Motherboards for Enterprise applications.

- **Strategic JV & Tech Transfer**

As part of JV with MiTAC-Synnex Group (2017), Sahasra initiated MB manufacturing in India in 2019 via tech transfer from MiTAC Taiwan.

- **Commercial Expansion**

Leveraging extensive experience in enterprise server MBs, expanded into Consumer/Commercial MB space guided by MiTAC.

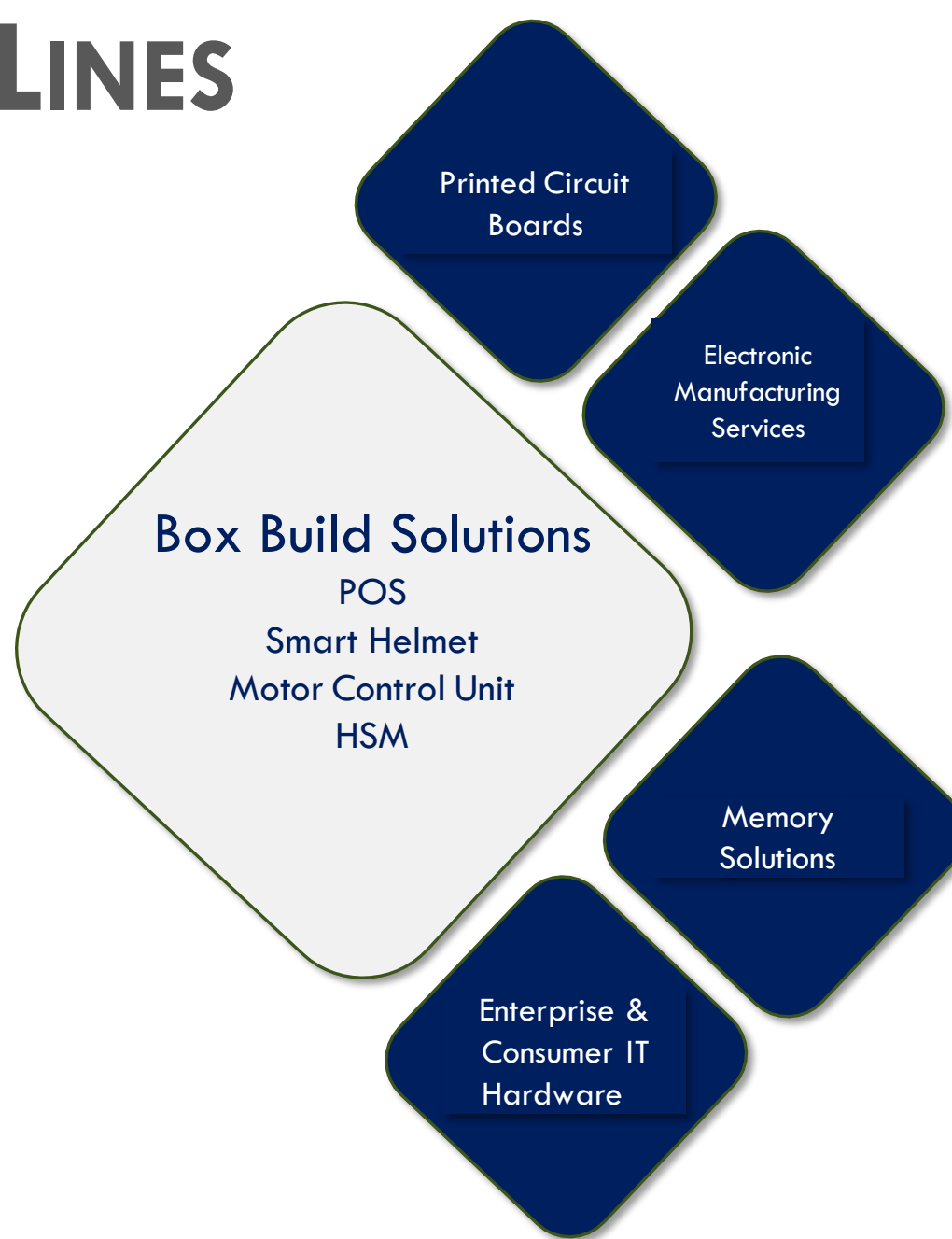
- **Next-Gen CPU Support**

Currently manufacturing 12th / 13th / 14th Gen Alder Lake & Raptor Lake CPU-based Desktop MBs for OEMs and channel markets in India & overseas.

- **Ecosystem Partnerships**

Signed OEM agreement for porting original Microsoft software at factory level, deepening IT hardware integration.

PRODUCT LINES



BOX BUILD SOLUTIONS

IoT-enabled protective headgear integrating communication modules, sensors, and worker safety tracking.



Instant audio payment notification device engineered for merchant QR transactions and retail POS systems



High-security physical computing device dedicated to cryptographic key management and enterprise encryption.



Next-generation digital power monitoring hardware built for smart grid metering and industrial power distribution.



Automotive video telemetry systems with high-definition recording and driver assistance technology.





INDUSTRIES CURRENTLY SERVED



Aerospace



Automotive



Industrial



Metering



Defence



Medical



Fintech



Railways

And Many more

SAHASRA SEMICONDUCTORS

“Packaged in India, trusted by the world”


Sahasra Semiconductors

INDIA's First Operational OSAT

Wafer Processing, IC Packaging & IC Test



SAHASRA GROUP'S ADVANCED OSAT/ATMP FACILITY



Sahasra: Powering India's Rise as a Global Memory Manufacturing Hub

Full Turnkey Solutions

- ❖ Wafer sort / Die sort
- ❖ Assembly
- ❖ Testing & Packaging

Value Added Services

- ❖ Die design
- ❖ Lead Frame design
- ❖ Failure Analysis & Reliability Testing
- ❖ Test Program Development & Product Characterization

Compliance & Certifications



8,000 Sq.Mtr.
Total Facility Area

4,000 Sq.Mtr.
Clean Room Area

10K & 100K
Clean Room Class

60 Million
Units Annual Capacity

R&D, FA, Reliability
Dedicated Laboratories

PLI & SPECS
Approved Schemes



CLEAN ROOM ENVIRONMENT

MACHINES – CLASS10K

(FRONT OF THE LINE)



MACHINES – CLASS100K

(END OF THE LINE)



MACHINES - TESTING



Quality is an integral part of the product at Sahasra Semiconductors, to ensure the same we have the latest state of the art equipment for the testing of the product before it is shipped.



MACHINES – FA & RELIABILITY



Robust FA and reliability processes uncover root causes of defects and validate long-term device performance, enabling higher yields and more dependable products. Sahasra Semiconductors has the latest technology so that each product meets the stringent industry standards.

SERVICES



Full Stack

Wafer Back Grinding
Laser Grooving
Mechanical Dicing
Die Bonding
Wire bonding
Saw Singulation, Trim & form,
Package Dicing
Laser Marking, Laser Curve Cut
Digital, Analog & Mixed Signal
Testing

Value Add

Material sourcing
Inventory management
Die banking
Tape & Reel, tube & tray packing
Labelling & Marking
Serialization & traceability systems
Custom Packages & Lead Frame
design
Interposer Design
FA & Reliability

PRODUCT PORTFOLIOS

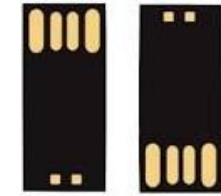


Package Type	Production Started in
MicroSD	Oct 2024
eSIM IC	Feb 2025
LED Driver IC	Jun 2025
RFID IC	Jan 2026



MEMORY PACKAGE PORTFOLIO

Package Type	When	Remarks
Micro SD Memory	In Production	
COB/UDP*	Q1-2026	Trial Production
COB/UDP*	Q3-2026	Mass Production

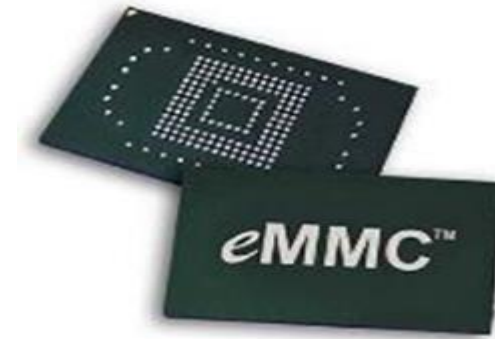


- All Substrate packages comply to ROHS/Green Mfg
- Substrate Design In-house



MEMORY PACKAGE PORTFOLIO (FUTURE PROJECTIONS)

Package Type	When	Remarks
Micro SD Memory	In Production	
eMMC/eSSD*	Q2/Q3-2027	Trial Production
eMMC/eSSD*	Q4-2027	Mass Production



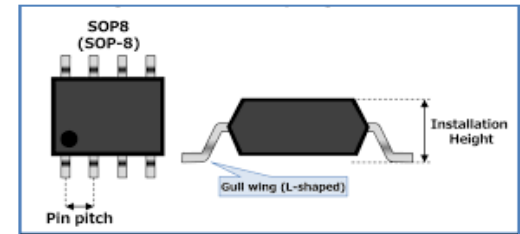
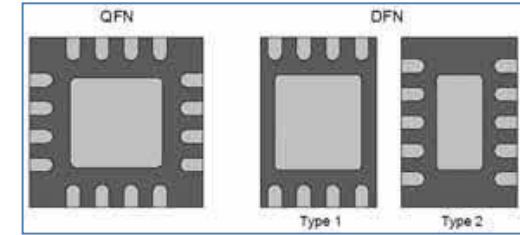
- All Substrate packages comply to ROHS/Green Mfg
- Substrate Design In-House
- Post Phase – II Equipment Upgradation
- Embedded packages compliant with JEDEC eMMC 5.0/5.1
- PCIe Gen 3x2 and SATA 3.0 protocol for BGA SSD
- MLC/TLC Nand Flash and eMMC Controller in 1 package
- Embedded and IoT applications



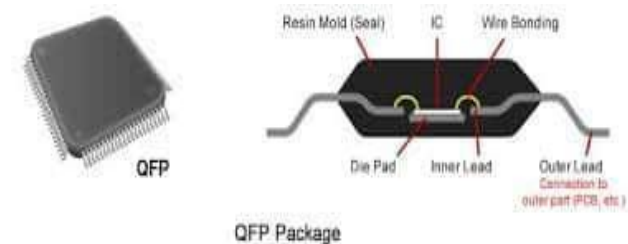
SOP & QFN/DFN PACKAGE PORTFOLIO



Package Type	When	Remarks
ESOP – 7/8	Available	Exposed Pad with Downset
QFN/DFN	Available	0.75mm Thickness
UQFN/UDFN	Q2-2026	0.40/0.50mm Thickness
QFN/DFN/DSN/SON	Q4-2026	0.90mm Thickness

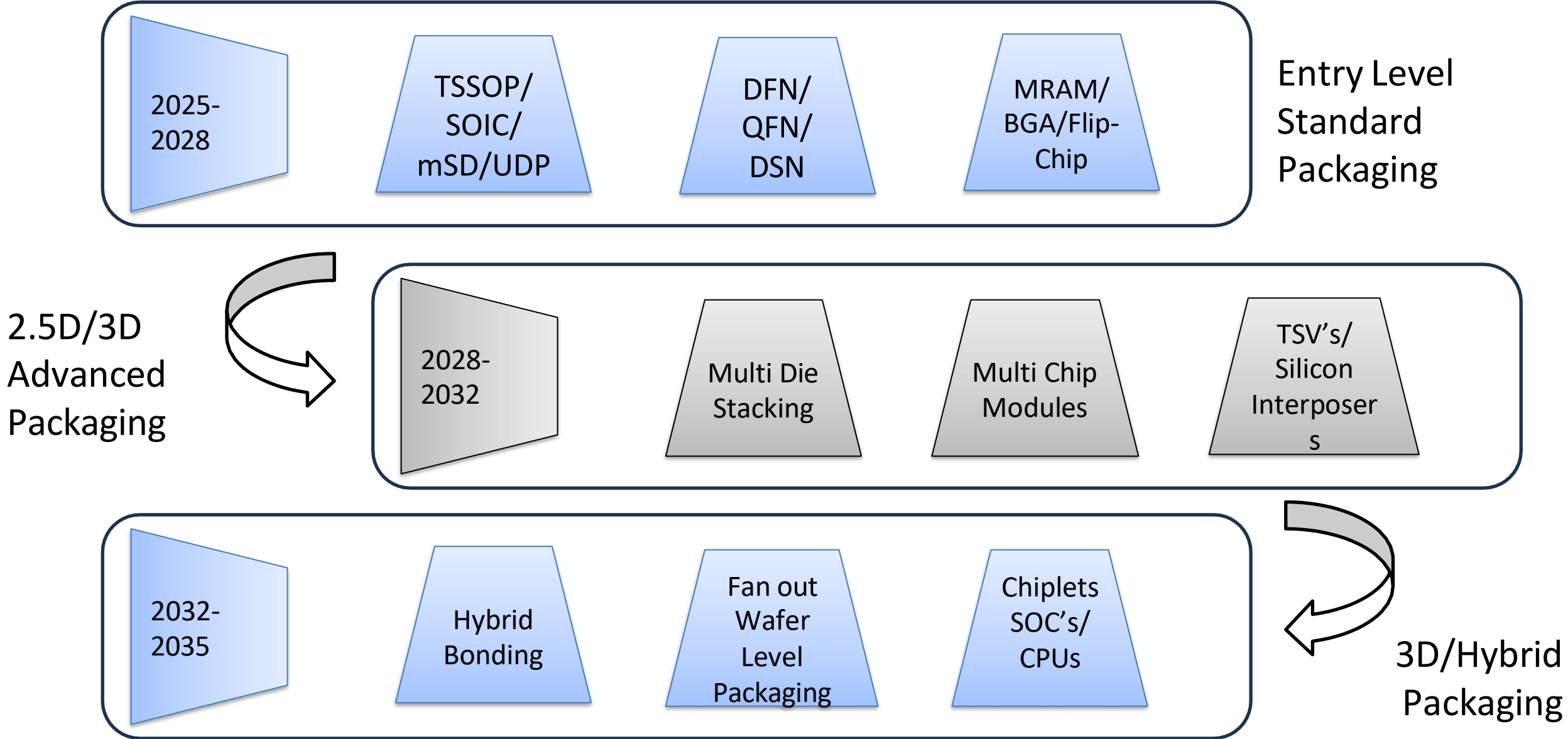


- All Lead-frame based packages comply to ROHS / Green
- Multiple surface finish options are available 100% Sn / NiPdAu
- Analog/Digital/Mixed Signal/RF

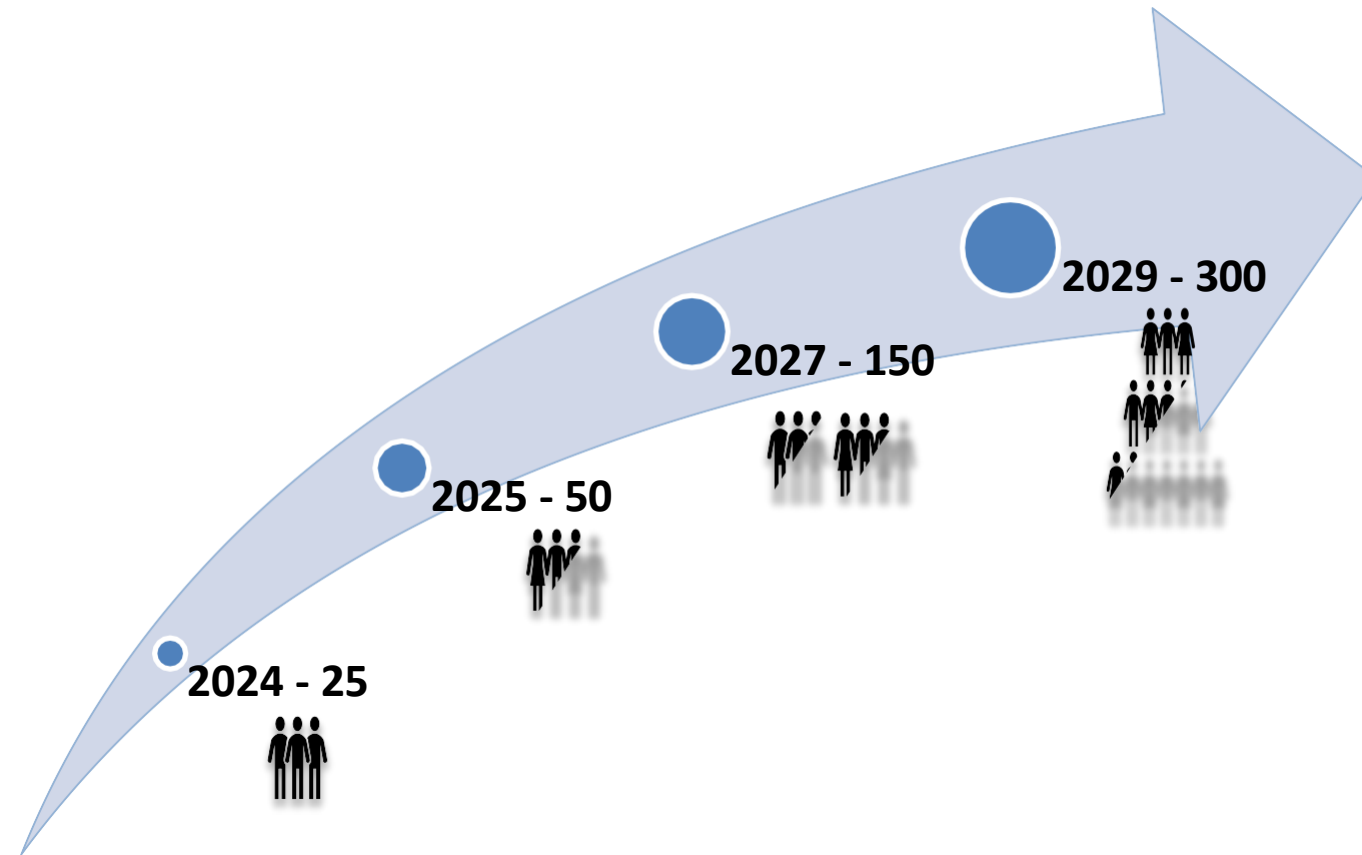




PACKAGE ROADMAP



HIGH SKILLED MANPOWER – GROWING DIRECT EMPLOYMENT



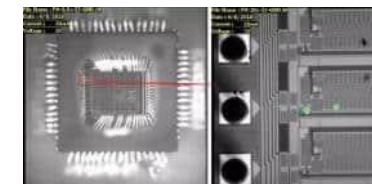
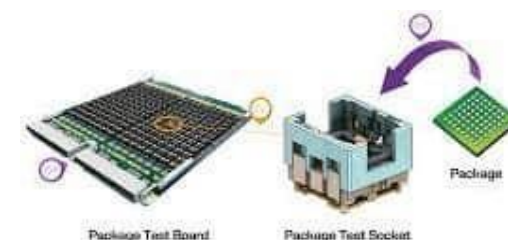
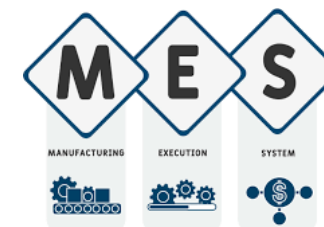
Sahasra Semiconductors extends its facilities to train human capital:

- MoU with Universities for lab sessions as part of Engineering curriculum
- On Job Training for hands on exposure
- Working with Universities on designing curriculums to train industry ready Engineers
- Hiring skilled expat human resources to enable the learning curve to grow faster



CERTIFICATIONS & SYSTEMS

- ISO 9001:2015 SO 14001 & ISO 45001 certified
- IATF 16949 planned for June 2027
- SAP S/4 HANA ERP Live since 1st September 2026
- MES System onboarding in process
- Test Program Development & Testing Services
- Providing Failure Analysis & Reliability Test services



FINANCIAL HIGHLIGHTS



Performance update and management commentary FY26



Business updates

- Majority focus towards NAND Flash Memory production with demand being at all time high due to the Memory Super Cycle as AI demand expands. Exports are driving growth with over 60% of revenue contribution
- Development of other packages such as 48TQFP¹, 68QFN² and UDP³ which will add to product mix and revenue contribution in the next few quarters
- 2 more lines installed at SESL including box build and coating line, large scale manufacturing potentials being targeted such as automotive, solar, energy, IOT modules. Strengthening memory and IT hardware test & reliability infra



Financial highlights

- Revenue grew by **45% YoY** in FY26 to INR 138.8 cr
- EBITDA was **INR 18.2 cr** in FY26 with margins at **13.1%**
- **PAT grew by 617% YoY** in FY26 to INR **12.1 cr** with margins at **8.7%**



Management commentary

- Targeting consolidated **revenue of ₹325 cr** by FY2027 post merger
- Aiming to establish Sahasra as an Original Design Manufacturer (ODM) in IT hardware and memory domain with in-house substrate design capabilities
- Strengthening risk management through diversification of product portfolio and expansion of client base across geographies. India pivot is contributing to 45% of revenue mitigating global market risks
- **Investing ₹200 cr** in semiconductor expansion and **₹50 cr in R&D** to build high-value IP and future capabilities
- We are applying to ISM 2.0 and Rajasthan Semiconductor Policy 2026



Q1 FY27 Performance

₹ crore unless otherwise mentioned		
SESL	Q1 FY27	Q1 FY26
Q1 Financials		
Revenue	32.96	20.42
Other Income	2.10	1.00
Total Income	35.06	21.42
EBIDTA	6.53	3.64

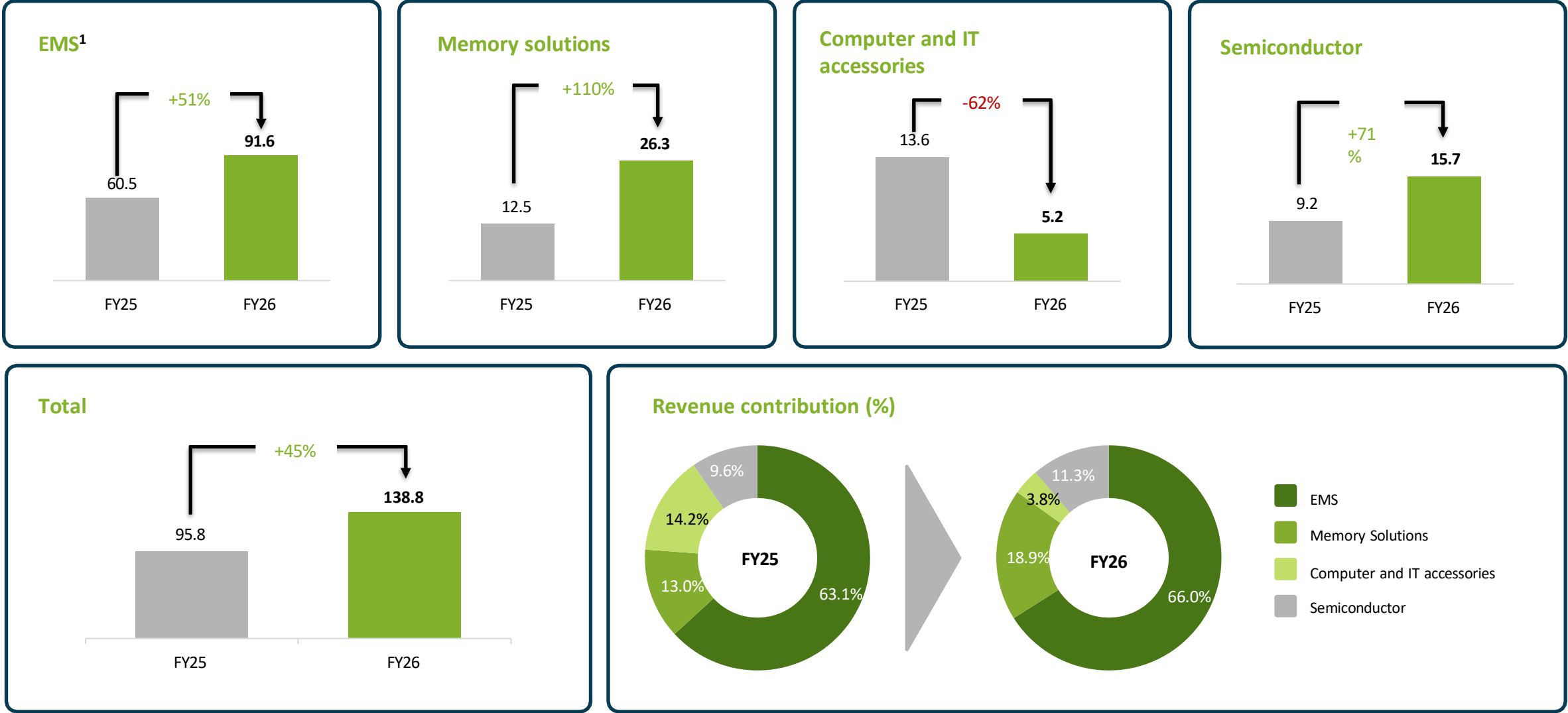
₹ crore unless otherwise mentioned		
Consolidated	Q1 FY27	Q1 FY26
Q1 Financials		
Revenue	47.90	22.03
Other Income	2.32	1.00
Total Income	50.22	23.04
EBIDTA	7.29	2.97



Quarter Snapshot

- Sahasra Semiconductors Pvt Limited, Bhiwadi Unit inaugurated by Hon’ble Chief Minister of Rajasthan Shri Bhajan Lal Sharma, Hon’ble Union Minister Shri Ashwini Vaishnaw, Hon’ble Union Minister Shri Bhupender Yadav, Shri Sanjay Sharma and Shri S. Krishnan, Secretary, MeITY on May 15, 2026.
- Ultramax Sahasra Energy Private Limited incorporated. This is a JV between Ultramax, United Kingdom & Sahasra Group India and this entity will be in manufacturing of battery packs and related products
- The revenue showed an increase of around 60% QoQ.
- Two new SMT lines have been installed at the Bhiwadi EMS Facility. This quarter we have also forayed into working for the Fintech space.

Revenue split across segments – FY26 *(Based on consolidated numbers)*



1. EMS: Electronics manufacturing services



Export Vs Domestic Split

Q1 FY27 (Standalone)

Segment	Amount (INR crs)	Percentage of Total
Export Sale	21.66	66%
Domestic Sale	11.30	34%
Total	32.96	

Q1 FY27 (Consolidated)

Segment	Amount (INR crs)	Percentage of Total
Export Sale	32.01	66.83%
Domestic Sale	15.89	33.17%
Total	47.90	



Order Book *(consolidated numbers)*

Unit	Projected Revenue (INR crs)	Revenue Q1FY27 (INR crs)	Open Order Book (INR crs)
SESL	150	32.96 (22%)	75 (50%)
SSPL	50	14.94 (30%)	18 (36%)
Total	200	47.90 (24%)	93 (47%)

Advanced manufacturing infrastructure with scalable operations



UNIT 1

Noida

Capacity	Area
6 million	2,100 sq.mtr.
	SMT lines
	4



Peak revenue	2026 revenue
100 cr	78.7cr
Peak Utilization	2026 utilization
100%	78.7 %

UNIT 2

Bhiwadi

Capacity	Area
18 million	2,870 sq.mtr.
	SMT lines
	4



Peak revenue	2026 revenue
400.0 cr	44.9 cr
Peak Utilization	2026 utilization
100%	22.5 %

UNIT 3

Bhiwadi(semicon)

Capacity	Area
60 million	6,000 sq.mtr.
	Clean rooms
	10k and 100k



Peak revenue	2026 revenue
250.0 cr	15.3 cr
Peak Utilization	2026 utilization
100%	6.1%



Strategic priorities to drive scalable growth

01



Diversification across high-growth product segments

- Expanding portfolio across PCBA, IT hardware, memory and semiconductor-linked products
- Increasing focus on products with higher growth and profitability potential, including IOT, enterprise computing and IP-led solutions
- Leveraging in-house R&D to develop Sahasra IP products and enhance value addition

02



Strategic expansion into semiconductor ecosystem

- Entry into semiconductor packaging through subsidiary acquisition
- Building capabilities across ICs, memory devices and advanced components
- Strengthens positioning in a high-value, fast-growing segment of electronics value chain

03



Market expansion and geographic diversification

- Expanding presence across new international markets with focus on Europe
- Diversifying geographies to mitigate concentration risks including US tariff exposure
- Strengthening relationships with global OEMs and increasing wallet share

04



Capacity expansion and technology investments

- Investing in automation, process optimization and manufacturing scale-up
- Enhancing capabilities to support complex, high-mix manufacturing requirements
- Driving cost efficiency and operating leverage through scale

05



Inorganic growth and strategic partnerships

- Pursuing targeted acquisitions to expand capabilities and product portfolio
- Leveraging partnerships to enter new geographies and access new customers
- Enhancing scale, market position and cross-selling opportunities

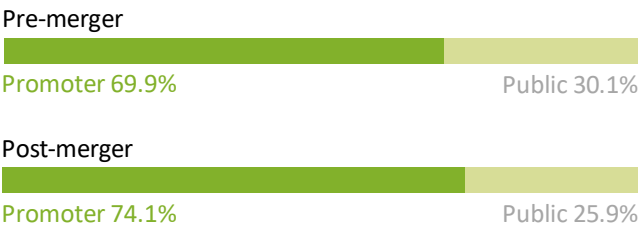
Group structure and business areas

Entity	Role	Business description
SESL	Listed	Manufacturing & assembly of electronic products, populated PCBs
SSPL	Subsidiary	Semiconductors
SEPL	To be merged	Manufacture, assembly & trading of electrical products
ITPL	To be merged	Manufacturing of printed circuit boards (PCBs)
SSSDPL	To be merged	Skill development & vocational training in electronics
Optima Tech.	Independent	Electronic contract manufacturing & assembly of PCBs, box builds & electronic systems
Megma RFID	Independent	Manufacturing & sale of RFID tags, labels & tracking solutions for goods, assets & people
SEPL Rwanda	Overseas sub	Wholly owned subsidiary of SEPL

Share swap ratios

SEPL : SESL	226 : 100
ITPL : SESL	5 : 100
SSSDPL : SESL	55 : 100

Merger impact on SESL’s shareholding



Based on fully diluted shareholding as on 31 Dec 2025

Strategic rationale

-  Consolidate complementary electronics manufacturing, PCB & skilling operations under a single listed entity
-  Eliminate duplication of functions; optimise financial & operational resources
-  Improve cost structures, market positioning & governance framework
-  Enable organic & inorganic growth partnerships, acquisitions & market expansion

Safe harbor statement



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Thank you

For further information, please contact:

COMPANY



SAHASRA ELECTRONICS SOLUTIONS LIMITED

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